

 Drafts

ISNR:

ISNR:

BRS:

BRS: bios

 Pending

 Active

L1: (4230) ic same thermal

L2: (2) adaptive same 1

L3: (265) ic and (thermal adj4 manage\$5)

L4: (27) overclock\$3

L6: (0) 1 and 4

L7: {0} 3 and 4

L5: (107) 1 and 3

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L8: (8100) bios
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L9: (6) 4 and 8

L10: (2) 3 and 8

L11: (1) "5825972".PN.

L12: (1) "5460009".PN.

L13: (1) "5457766".PN.

L14: (1) "5197858". PN.

L15: (1) "5099181".PN.

L16: (1) "4168456".PN.

L17: (7) overclock\$3 and (thermal adj 4 manage\$5)

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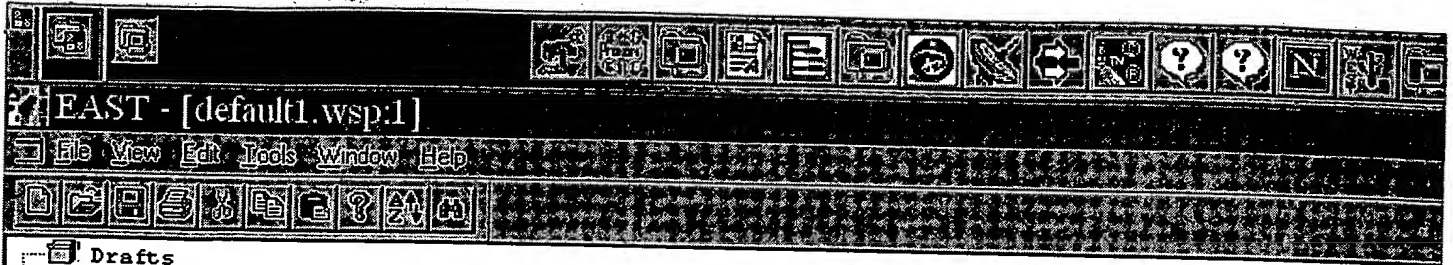
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1 Advances in IC packaging, interconnect and assembly
Sage, M.;
Electronic Manufacturing Technology Symposium, 1988, Fourth IEEE/CHMT Eur
International , 13-15 June 1988
Page(s): 76 -79

[\[Abstract\]](#) [\[PDF Full-Text \(176 KB\)\]](#) **IEEE CNF**

2 Quality issues of high pin count fine pitch VLSI packages
Hnatek, E.R.; Livesay, B.R.;
Test Conference, 1989. Proceedings. 'Meeting the Tests of Time'. , International
Aug. 1989
Page(s): 397 -421

[\[Abstract\]](#) [\[PDF Full-Text \(1372 KB\)\]](#) **IEEE CNF**

3 Packaging for a 1 Gb/s OEIC fiber-optic data link
*Jackson, K.P.; Flint, E.B.; Cina, M.F.; Moll, A.J.; Ewen, J.F.; Flagello, D.; Rand,
Purushothaman, S.;*
Electronic Components Conference, 1989. Proceedings., 39th , 22-24 May 1989
Page(s): 374 -377

[\[Abstract\]](#) [\[PDF Full-Text \(312 KB\)\]](#) **IEEE CNF**

**4 3-D wafer-scale interconnect and packaging using photosensitive
glass-ceramic substrates**
Jacobi, W.J.; Reche, J.J.H.;

Aerospace and Electronics Conference, 1989. NAECON 1989., Proceedings of the 1989 National , 22-26 May 1989
Page(s): 4 -8 vol.1

[\[Abstract\]](#) [\[PDF Full-Text \(264 KB\)\]](#) **IEEE CNF**

5 GaAs HBTs: an analog circuit design perspective

Corcoran, J.; Poulton, K.; Knudsen, K.;

Bipolar Circuits and Technology Meeting, 1991., Proceedings of the 1991 , 9-10 1991

Page(s): 245 -252

[\[Abstract\]](#) [\[PDF Full-Text \(712 KB\)\]](#) **IEEE CNF**

6 Multichip module enables for high reliability applications

Chu, D.; Reber, C.A.; Draper, B.L.; Sweet, J.N.; Palmer, D.W.;

Multi-Chip Module Conference, 1992. MCMC-92, Proceedings 1992 IEEE , 18-20 1992

Page(s): 102 -105

[\[Abstract\]](#) [\[PDF Full-Text \(328 KB\)\]](#) **IEEE CNF**

7 High density overlay interconnect (HDI) delivers high frequency performance for GaAs systems

Gdula, M.; Haller, T.; Krishnamurthy, V.; Forman, G.;

Multi-Chip Module Conference, 1993. MCMC-93, Proceedings., 1993 IEEE , 15-1 March 1993

Page(s): 33 -38

[\[Abstract\]](#) [\[PDF Full-Text \(524 KB\)\]](#) **IEEE CNF**

8 Experience with nondestructive acoustic inspection of power IC's

Moore, T.M.; Frank, K.A.;

Electronic Components and Technology Conference, 1995. Proceedings., 45th , May 1995

Page(s): 305 -314

[\[Abstract\]](#) [\[PDF Full-Text \(2524 KB\)\]](#) **IEEE CNF**

9 Microwave power heterojunction bipolar transistors fabricated with t shunt and bathtub

Bozada, C.A.; Barlage, D.W.; Barrette, J.P.; Dettmer, R.W.; Mack, M.P.; Sewell Via, G.D.; Yang, L.W.; Helms, D.R.; Komiak, J.J.;

Gallium Arsenide Integrated Circuit (GaAs IC) Symposium, 1995. Technical Dig

1995., 17th Annual IEEE , 29 Oct.-1 Nov. 1995

Page(s): 155 -158

[\[Abstract\]](#) [\[PDF Full-Text \(480 KB\)\]](#) **IEEE CNF**

10 Thermal management to avoid the collapse of current gain in power heterojunction bipolar transistors

Liu, W.;

Gallium Arsenide Integrated Circuit (GaAs IC) Symposium, 1995. Technical Dig 1995., 17th Annual IEEE , 29 Oct.-1 Nov. 1995

Page(s): 147 -150

[\[Abstract\]](#) [\[PDF Full-Text \(416 KB\)\]](#) **IEEE CNF**

11 Low cost packaging techniques for commercial GaAs IC components

Steel, V.;

Gallium Arsenide Integrated Circuit (GaAs IC) Symposium, 1996. Technical Dig 1996., 18th Annual , 3-6 Nov. 1996

Page(s): 18 -20

[\[Abstract\]](#) [\[PDF Full-Text \(232 KB\)\]](#) **IEEE CNF**

12 Transient thermal management in electronic packaging using dynam control of power dissipation and heat transfer

Cao, L.; Krusius, J.P.; Korhonen, M.; Fisher, T.;

Electronic Components and Technology Conference, 1996. Proceedings., 46th , May 1996

Page(s): 205 -211

[\[Abstract\]](#) [\[PDF Full-Text \(700 KB\)\]](#) **IEEE CNF**

13 Thermal management of packaged IC by experimentally verified finite element modeling

Pape, H.; Beyfuss, M.; Kutscherauer, R.;

Electronic Packaging Technology Conference, 1997. Proceedings of the 1997 1st Oct. 1997

Page(s): 58 -64

[\[Abstract\]](#) [\[PDF Full-Text \(864 KB\)\]](#) **IEEE CNF**

14 Comparison of electrical performance of enhanced BGAs

Kaw, R.; Hanna, B.; Devnani, N.;

Electronic Components and Technology Conference, 1997. Proceedings., 47th , May 1997

Page(s): 682 -688

[\[Abstract\]](#) [\[PDF Full-Text \(604 KB\)\]](#) **IEEE CNF**

15 Thermal management of microelectronics in the 21st century

Bar-Cohen, A.;

Electronic Packaging Technology Conference, 1997. Proceedings of the 1997 1st
Oct. 1997

Page(s): 29 -33

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